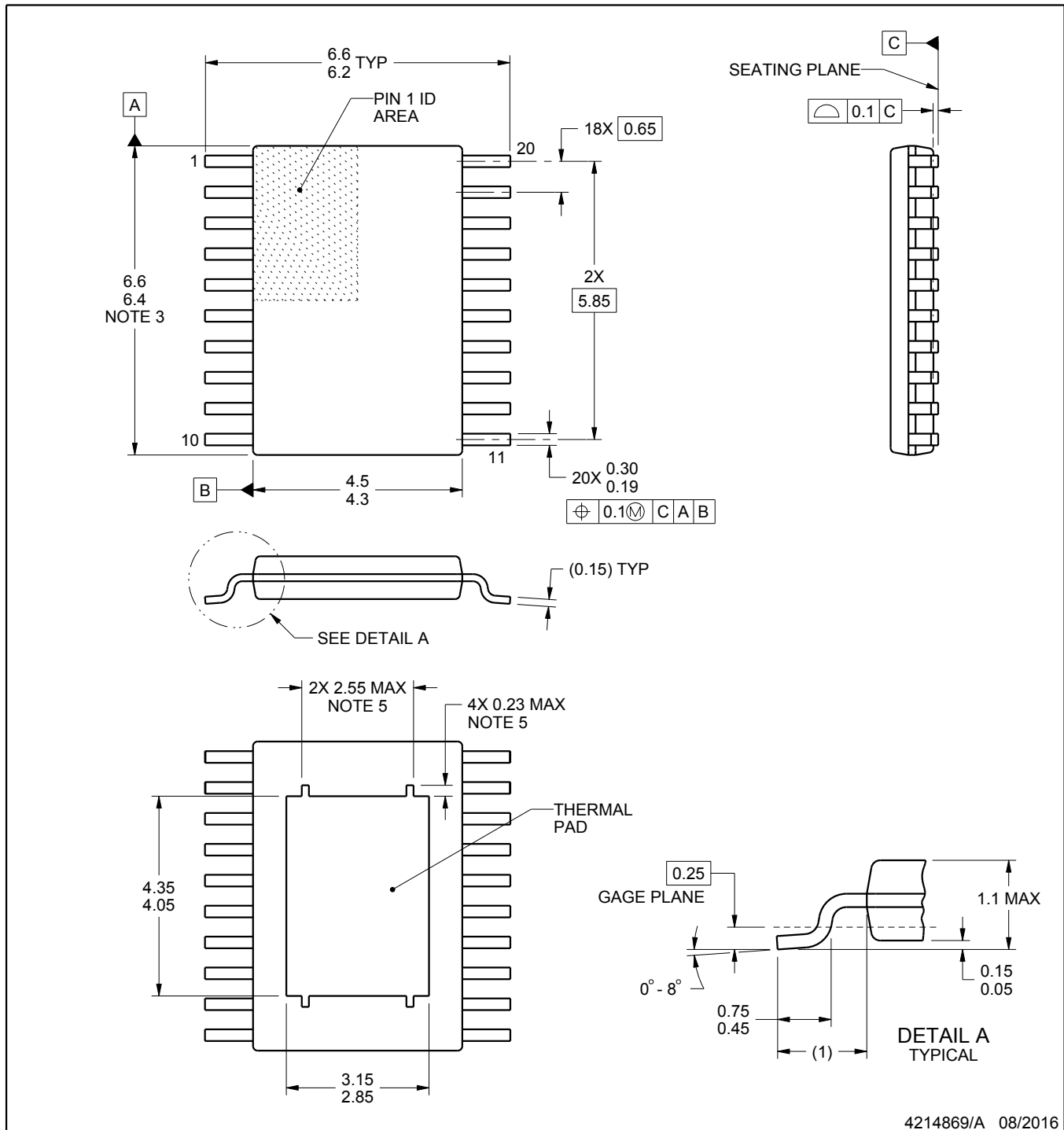
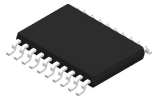


DATA BOOK
PACKAGE OUTLINE

LEADFRAME EXAMPLE
4212903

DRAFTER:	T. LEQUANG	DATE:	08/02/2016			DIMENSIONS IN MILLIMETERS		
DESIGNER:		DATE:		 TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS CODE IDENTITY NUMBER 01295 ePOD, PWP0020A / TSSOP, 20 PIN, 0.65 MM PITCH				
CHECKER:	K. SINCERBOX & V. PAKU	DATE:	06/23/2016					
ENGINEER:	A. FAUZI	DATE:	08/02/2016					
APPROVED:	E. REY	DATE:	08/02/2016					
RELEASED:	WDM	DATE:	08/02/2016					
TEMPLATE INFO:	EDGE# 4218519	DATE:	03/20/2013	SCALE 8X	SIZE A	4214869	REV A	PAGE 1 OF 5



4214869/A 08/2016

NOTES:

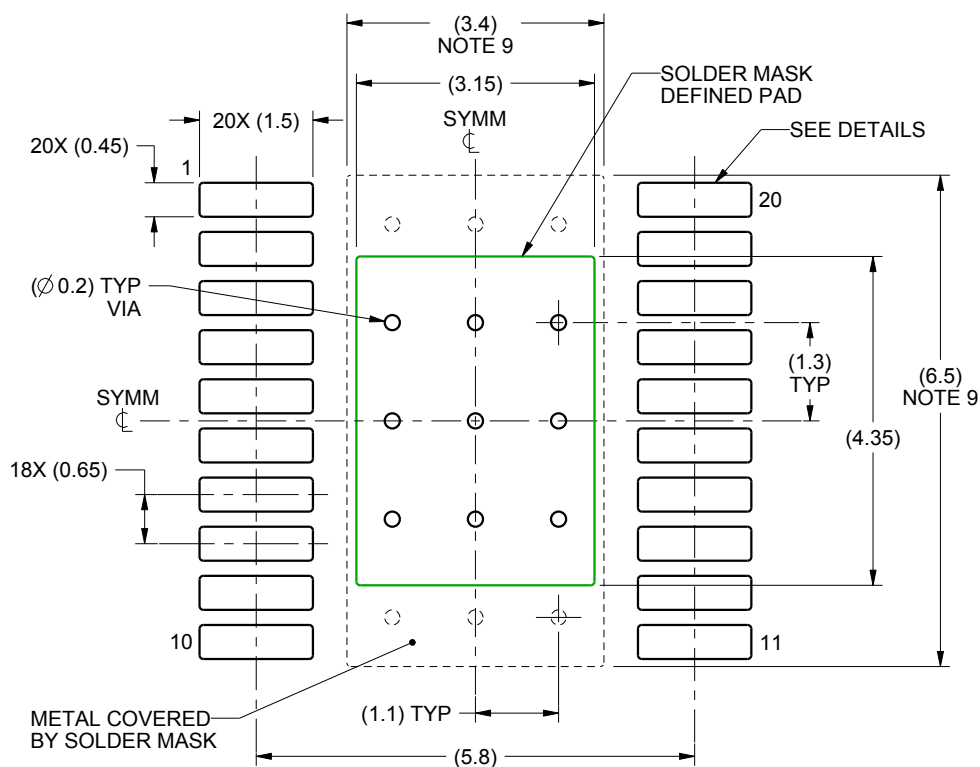
PowerPAD is a trademark of Texas Instruments.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.
5. Features may differ or may not be present.

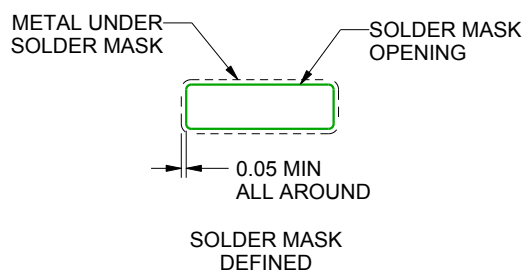
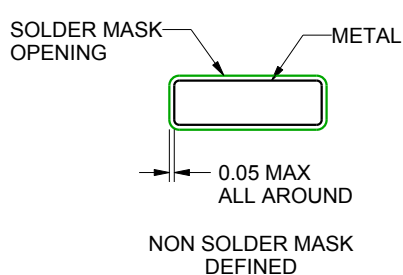
PWP0020A

PowerPAD™ TSSOP - 1.1 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS

PADS 1-20

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NOTES: (continued)

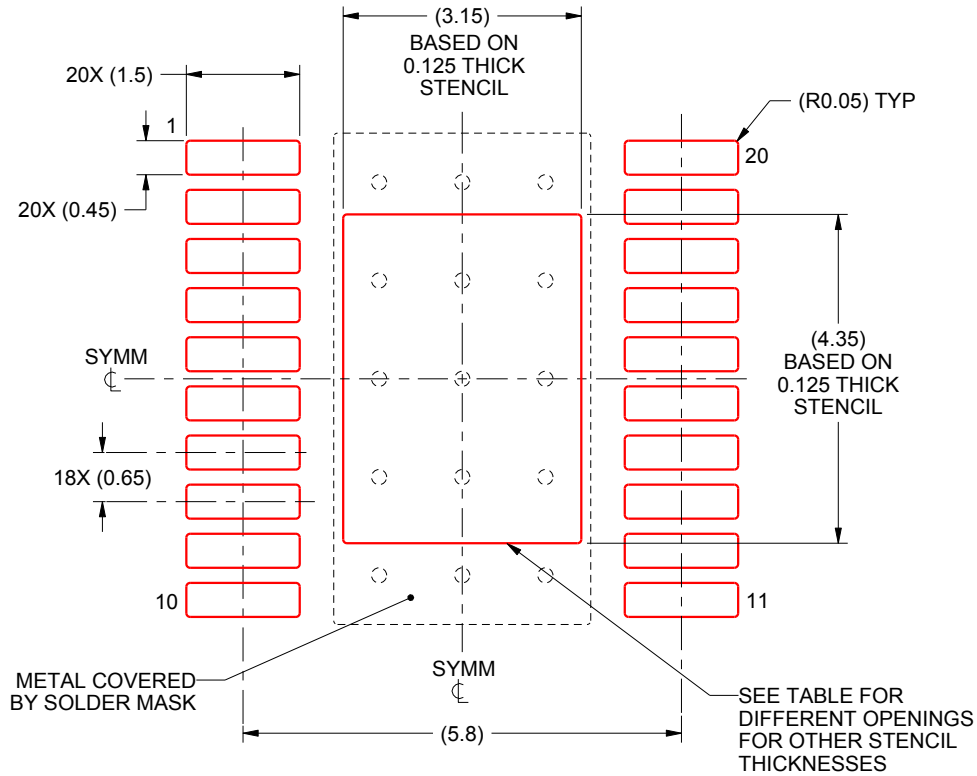
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.

EXAMPLE STENCIL DESIGN

PWP0020A

PowerPAD™ TSSOP - 1.1 mm max height

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE
EXPOSED PAD
100% PRINTED SOLDER COVERAGE BY AREA
SCALE:10X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	3.52 X 4.86
0.125	3.15 X 4.35 (SHOWN)
0.15	2.88 X 3.97
0.175	2.66 X 3.68

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NOTES: (continued)

10. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
11. Board assembly site may have different recommendations for stencil design.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2158725	08/02/2016	A. FAUZI / T. LEQUANG